



# MULTIFUNCTION QUAD POWER AMPLIFIER WITH BUILT-IN DIAGNOSTICS FEATURES

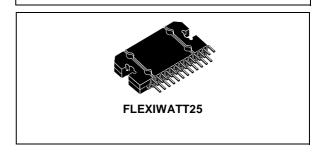
- DMOS POWER OUTPUT
- HIGH OUTPUT POWER CAPABILITY 4x25W/ 4W @ 14.4V, 1KHZ, 10% THD, 4x35W EIAJ
- MAX. OUTPUT POWER 4x60W/2W
- FULL I2C BUS DRIVING:
  - ST-BY
  - INDEPENDENT FRONT/REAR SOFT PLAY/ MUTE
  - SELECTABLE GAIN 26dB 12dB (FOR LOW NOISE LINE OUTPUT FUNCTION)
  - I<sup>2</sup>C BUS DIGITAL DIAGNOSTICS
- **FULL FAULT PROTECTION**
- DC OFFSET DETECTION
- FOUR INDEPENDENT SHORT CIRCUIT PROTECTION
- CLIPPING DETECTOR
- ESD PROTECTION

#### **DESCRIPTION**

The TDA7561 is a new BCD technology QUAD BRIDGE type of car radio amplifier in Flexiwatt25

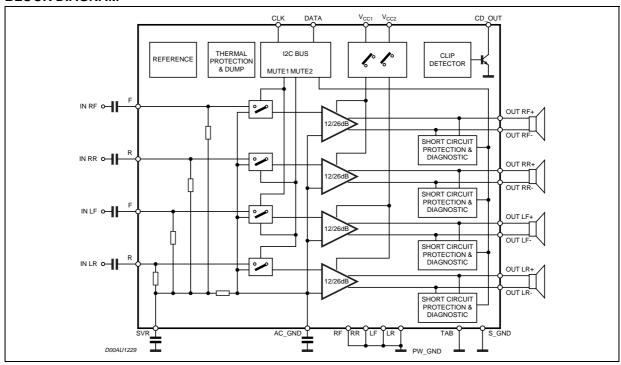
#### **MULTIPOWER BCD TECHNOLOGY**

#### MOSFET OUTPUT POWER STAGE



package specially intended for car radio applications. Thanks to the DMOS output stage the TDA7561 has a very low distortion allowing a clear powerful sound. This device is equipped with a full diagnostics array that communicates the status of each speaker through the I<sup>2</sup>C bus. The possibility to control the configuration and behaviour of the device by means of the I<sup>2</sup>C bus makes TDA7561 a very flexible machine.

#### **BLOCK DIAGRAM**



December 2002 1/19

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>op</sub>	Operating Supply Voltage	18	V
Vs	DC Supply Voltage	28	V
V <sub>peak</sub>	Peak Supply Voltage (for t = 50ms)	50	V
Vck	CK pin Voltage	6	V
V <sub>DATA</sub>	Data Pin Voltage	6	V
Io	Output Peak Current (not repetitive t = 100ms)	8	А
Io	Output Peak Current (repetitive f > 10Hz)	6	А
P <sub>tot</sub>	Power Dissipation Tcase = 70°C	85	W
T <sub>stg</sub> , T <sub>j</sub>	Storage and Junction Temperature	-55 to 150	°C

# THERMAL DATA

Ī	Symbol	Parameter	Value	Unit
Ī	R <sub>th j-case</sub>	Thermal Resistance Junction to case Max.	1	°C

#### **PIN CONNECTION**

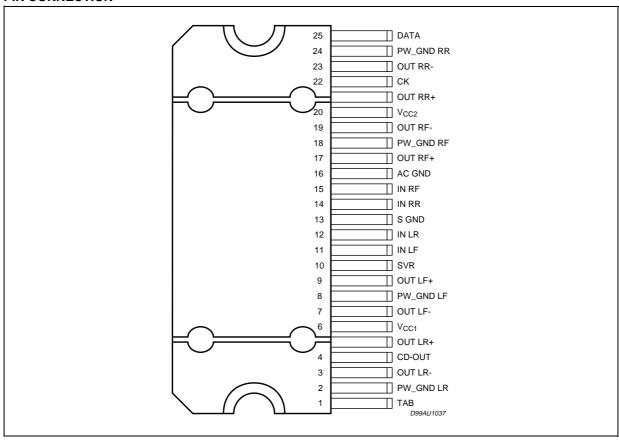
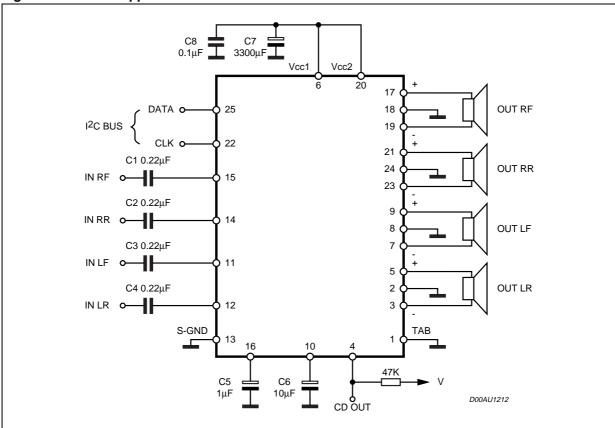


Figure 1. Test and Application Circuit



# **ELECTRICAL CHARACTERISTCS**

(Refer to the test circuit,  $V_S$  = 14.4V;  $R_L$  = 4 $\Omega$ ; f = 1KHz;  $T_{amb}$  = 25°C; unless otherwise specified).

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
POWER A	AMPLIFIER	•	•			
Vs	Supply Voltage Range		8		18	V
I <sub>d</sub>	Total Quiescent Drain Current			150	300	mA
Po	Output Power	EIAJ (V <sub>S</sub> = 13.7V)	32	35		W
		THD = 10%	22	25		W
		THD = 1%		20		W
		$R_L = 2\Omega$ ; EIAJ ( $V_S = 13.7V$ )	50	55		W
		$R_L = 2\Omega$ ; THD 10%	32	38		W
		$R_L = 2\Omega$ ; THD 1%		30		W
		$R_L = 2\Omega$ ; MAX POWER		60		W
THD	Total Harmonic Distortion	P <sub>O</sub> = 1W to 10W;		0.04	0.1	%
		$G_V = 12dB; V_O = 0.1 \text{ to } 5V_{RMS}$		0.02	0.05	%
C <sub>T</sub>	Cross Talk	$f = 1KHz$ to $10KHz$ , $R_G = 600\Omega$	50	60		dB
R <sub>IN</sub>	Input Impedance		80	100	130	ΚΩ
G <sub>V1</sub>	Voltage Gain 1		25	26	27	dB
$\Delta G_{V1}$	Voltage Gain Match 1		-1		1	dB
G <sub>V2</sub>	Voltage Gain 2		11	12	13	dB
$\Delta G_{V2}$	Voltage Gain Match 2		-1		1	dB
E <sub>IN1</sub>	Output Noise Voltage 1	Rg = 600Ω, 20Hz to 22kHz		35	80	μV
E <sub>IN2</sub>	Output Noise Voltage 2	Rg = $600\Omega$ ; G <sub>V</sub> = $12dB$ 20Hz to $22kHz$		12	20	μV
SVR	Supply Voltage Rejection	f = 100Hz to 10kHz; Vr = 1Vpk; Rg = 600Ω	50	60		dB
BW	Power Bandwidth		100			KHz
A <sub>SB</sub>	Stand-by Attenuation		90	110		dB
I <sub>SB</sub>	Stand-by Current			25	100	μΑ
A <sub>M</sub>	Mute Attenuation		80	100		dB
Vos	Offset Voltage	Mute & Play	-100	0	100	mV
V <sub>AM</sub>	Min. Supply Mute Threshold		7	7.5	8	V
T <sub>ON</sub>	Turn on Delay	D2/D1 (IB1) 0 to 1		20	40	ms
T <sub>OFF</sub>	Turn off Delay	D2/D1 (IB1) 1 to 0		20	40	ms

# **ELECTRICAL CHARACTERISTCS** (continued)

(Refer to the test circuit,  $V_S = 14.4V$ ;  $R_L = 4\Omega$ ; f = 1KHz;  $T_{amb} = 25$ °C; unless otherwise specified).

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
CD <sub>LK</sub>	Clip Det High Leakage Current	CD off		0	15	μΑ
CD <sub>SAT</sub>	Clip Det Sat. Voltage	CD on; I <sub>CD</sub> = 1mA		150	300	mV
CD <sub>THD</sub>	Clip Det THD level			1	2	%
TURN ON	DIAGNOSTICS 1 (Power Amplifier	Mode)				
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)	Power Amplifier in st-by condition			1.2	V
Pvs	Short to Vs det. (above this limit, the Output isconsidered in Short Circuit to V <sub>S</sub> )		Vs -1.2			V
Pnop	Normal operation thresholds. (Within these limits, the Output is considered without faults).		1.8		Vs -1.8	V
Lsc	Shorted Load det.				0.5	Ω
Lop	Open Load det.		130			Ω
Lnop	Normal Load det.		1.5		70	Ω
TURN ON	I DIAGNOSTICS 2 (Line Driver Mod	de)			•	
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)	Power Amplifier in st-by			1.2	V
Pvs	Short to Vs det. (above this limit, the Output isconsidered in Short Circuit to Vs)		Vs -1.2			V
Pnop	Normal operation thresholds. (Within these limits, the Output is considered without faults).		1.8		Vs -1.8	V
Lsc	Shorted Load det.				1.5	&
Lop	Open Load det.		400			&
Lnop	Normal Load det.		4.5		200	&
PERMAN	ENT DIAGNOSTICS 2 (Power Amp	lifier Mode or Line Driver Mode)				
Pgnd	Short to GND det. (below this limit, the Output is considered in Short Circuit to GND)	Power Amplifier in Mute or Play, one or more short circuits protection activated			1.2	V
Pvs	Short to Vs det. (above this limit, the Output is considered in Short Circuit to Vs)		Vs -1.2			V
Pnop	Normal operation thresholds. (Within these limits, the Output is considered without faults)		1.8		Vs -1.8	V

#### **ELECTRICAL CHARACTERISTCS** (continued)

(Refer to the test circuit,  $V_S = 14.4V$ ;  $R_L = 4\Omega$ ; f = 1KHz;  $T_{amb} = 25$ °C; unless otherwise specified).

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
Lsc	Shorted Load det.	Power Amplifier mode			0.5	Ω
		Line Driver mode			1.5	Ω
Vo	Offset Detection	Power Amplifier in play, AC Input signals = 0	1.5	2	2.5	V
I <sup>2</sup> C BUS I	<sup>2</sup> C BUS INTERFACE					
f <sub>SCL</sub>	Clock Frequency			400		KHz
V <sub>IL</sub>	Input Low Voltage				1.5	V
V <sub>IH</sub>	Input High Voltage		2.3			V

Figure 2. Quiescent Current vs. Supply Voltage

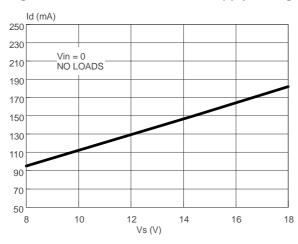


Figure 4. Output Power vs. Supply Voltage (4 $\Omega$ )

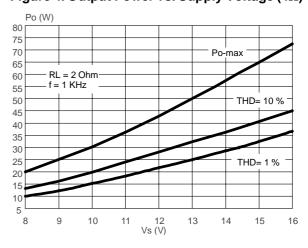


Figure 3. Output Power vs. Supply Voltage (2 $\Omega$ )

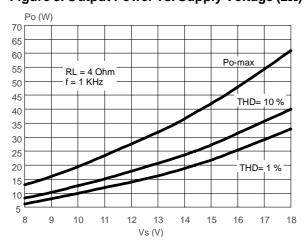


Figure 5. Distortion vs. Output Power (2 $\Omega$ )

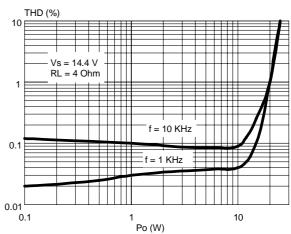


Figure 6. Distortion vs. Output Power (2 $\Omega$ )

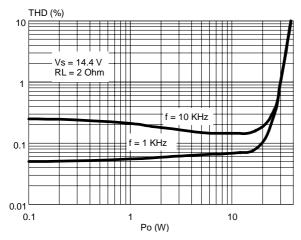


Figure 7. Distortion vs. Frequency (4 $\Omega$ )

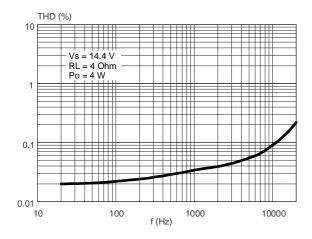


Figure 8. Distortion vs. Frequency (2 $\Omega$ )

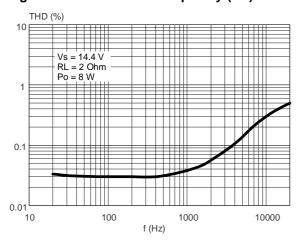


Figure 9. Crosstalk vs. Frequency

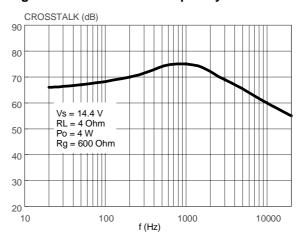


Figure 10. Supply Voltage Rejection vs.Frequency

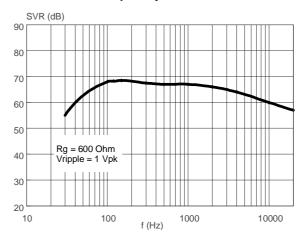


Figure 11. Power Dissipation & Efficiency vs.Output Power ( $4\Omega$ , SINE)

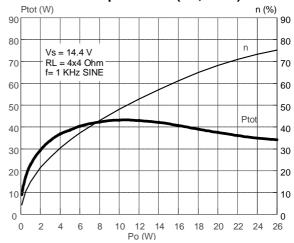


Figure 12. Power Dissipation vs. Average Ouput Power (Audio Program Simulation,  $4\Omega$ )

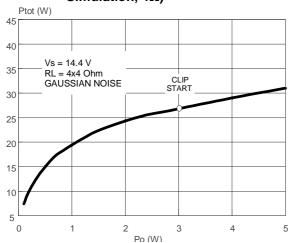
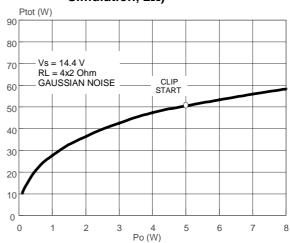


Figure 13. Power Dissipation vs. Average Ouput Power (Audio Program Simulation,  $2\Omega$ )



#### **DIAGNOSTICS FUNCTIONAL DESCRIPTION:**

#### a) TURN-ON DIAGNOSTIC.

It is activated at the turn-on (stand-by out) under I2Cbus request. Detectable output faults are:

- SHORT TO GND
- SHORT TO Vs
- SHORT ACROSS THE SPEAKER
- OPEN SPEAKER

To verify if any of the above misconnections are in place, a subsonic (inaudible) current pulse (fig. 14) is internally generated, sent through the speaker(s) and sunk back. The Turn On diagnostic status is internally stored until a successive diagnostic pulse is requested (after a I<sup>2</sup>C reading).

If the "stand-by out" and "diag. enable" commands are both given through a single programming step, the pulse takes place first (power stage still in stand-by mode, low, outputs = high impedance).

Afterwards, when the Amplifier is biased, the PERMANENT diagnostic takes place. The previous Turn On state is kept until a short appears at the outputs.

Figure 14. Turn - On diagnostic: working principle

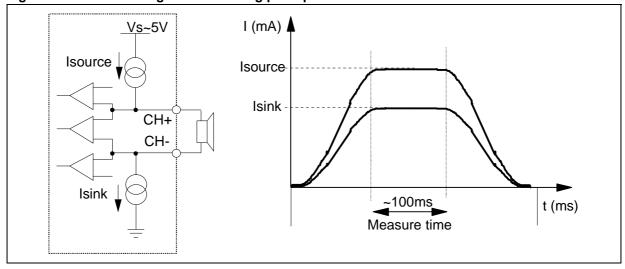


Fig. 15 and 16 show SVR and OUTPUT waveforms at the turn-on (stand-by out) with and without TURN-ON DIAGNOSTIC.

Out

Permanent diagnostic acquisition time (100mS Typ)

Bias (power amp turn-on)

Diagnostic Enable (Permanent)

FAULT event

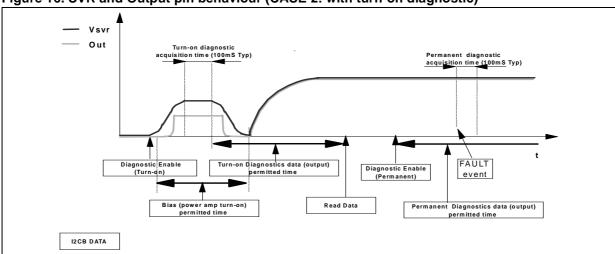
Read Data

Permanent Diagnostics data (output) permitted time

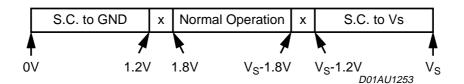
Figure 15. SVR and Output behaviour (CASE 1: without turn-on diagnostic)



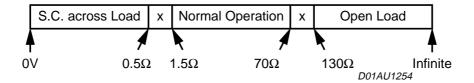
I2CB DATA



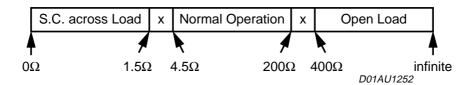
The information related to the outputs status is read and memorized at the end of the current pulse top. The acquisition time is 100 ms (typ.). No audible noise is generated in the process. As for SHORT TO GND / Vs the fault-detection thresholds remain unchanged from 26 dB to 12 dB gain setting. They are as follows:



Concerning SHORT ACROSS THE SPEAKER / OPEN SPEAKER, the threshold varies from 26 dB to 12 dB gain setting, since different loads are expected (either normal speaker's impedance or high impedance). The values in case of 26 dB gain are as follows:



If the Line-Driver mode (Gv= 12 dB and Line Driver Mode diagnostic = 1) is selected, the same thresholds will change as follows:



#### b) PERMANENT DIAGNOSTICS.

Detectable conventional faults are:

- SHORT TO GND
- SHORT TO Vs
- SHORT ACROSS THE SPEAKER

The following additional features are provided:

- OUTPUT OFFSET DETECTION

The TDA7561 has 2 operating statuses:

- 1) RESTART mode. The diagnostic is not enabled. Each audio channel operates independently from each other. If any of the a.m. faults occurs, only the channel(s) interested is shut down. A check of the output status is made every 1 ms (fig. 17). Restart takes place when the overload is removed.
- 2) DIAGNOSTIC mode. It is enabled via I<sup>2</sup>C bus and self activates if an output overload (such to cause the intervention of the short-circuit protection) occurs to the speakers outputs. Once activated, the diagnostics procedure develops as follows (fig. 18):
- To avoid momentary re-circulation spikes from giving erroneous diagnostics, a check of the output status is made after 1ms: if normal situation (no overloads) is detected, the diagnostic is not performed and the channel returns back active.
- Instead, if an overload is detected during the check after 1 ms, then a diagnostic cycle having a duration of about 100 ms is started.
- After a diagnostic cycle, the audio channel interested by the fault is switched to RESTART mode. The relevant data are stored inside the device and can be read by the microprocessor. When one cycle has terminated, the next one is activated by an I<sup>2</sup>C reading. This is to ensure continuous diagnostics throughout the car-radio operating time.
- To check the status of the device a sampling system is needed. The timing is chosen at microprocessor level (over half a second is recommended).

Figure 17. Restart timing without Diagnostic Enable (Permanent)

Each 1mS time, a sampling of the fault is done

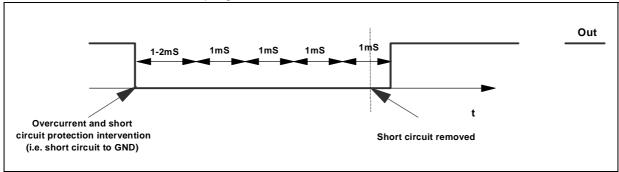
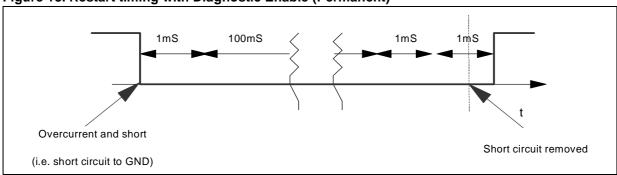


Figure 18. Restart timing with Diagnostic Enable (Permanent)



#### **OUTPUT DC OFFSET DETECTION.**

Any DC output offset exceeding ±2V are signalled out. This inconvenient might occur as a consequence of initially defective or aged and worn-out input capacitors feeding a DC component to the inputs, so putting the speakers at risk of overheating.

This diagnostic has to be performed with low-level output AC signal (or Vin = 0).

The test is run with selectable time duration by microprocessor (from a "start" to a "stop" command):START = Last reading operation or setting IB1 - D5 - (OFFSET enable) to 1STOP = Actual reading operation

Excess offset is signalled out if persistent throughout the assigned testing time. This feature is disabled if any overloads leading to activation of the short-circuit protection occurs in the process.

#### **MULTIPLE FAULTS.**

When more misconnections are simultaneously in place at the audio outputs, it is guaranteed that at least one of them is initially read out. The others are notified after successive cycles of  $l^2C$  reading and faults removal, provided that the diagnostic is enabled. This is true for both kinds of diagnostic (Turn on and Permanent).

The table below shows all the couples of possible double-fault. It should be taken into account that a short circuit with the 4 ohm speaker unconnected is considered as double fault.

Double fault table for Turn On Diagnostic

	S. GND (so)	S. GND (sk)	S. Vs	S. Across L.	Open L.
S. GND (so)	S. GND	S. GND	S. Vs + S. GND	S. GND	S. GND
S. GND (sk)	/	S. GND	S. Vs	S. GND	Open L. (*)
S. Vs	/	/	S. Vs	S. Vs	S. Vs
S. Across L.	/	/	/	S. Across L.	N.A.
Open L.	/	/	/	/	Open L. (*)

S. GND (so) / S. GND (sk) in the above table make a distinction according to which of the 2 outputs is shorted to ground (test-current source side= so, test-current sink side = sk). More precisely, so = CH+, sk = CH-.

In Permanent Diagnostic the table is the same, with only a difference concerning Open Load(\*), which is not among the recognisable faults. Should an Open Load be present during the device's normal working, it would be detected at a subsequent Turn on Diagnostic cycle (i.e. at the successive Car Radio Turn on).

#### **FAULTS AVAILABILITY**

All the results coming from I<sup>2</sup>Cbus, by read operations, are the consequence of measurements inside a defined period of time. If the fault is stable throughout the whole period, it will be sent out.

To guarantee always resident functions, every kind of diagnostic cycles (Turn on, Permanent, Offset) will be reactivate after any  $I^2C$  reading operation. So, when the micro reads the  $I^2C$ , a new cycle will be able to start, but the read data will come from the previous diag. cycle (i.e. The device is in Turn On state, with a short to Gnd, then the short is removed and micro reads  $I^2C$ . The short to Gnd is still present in bytes, because it is the result of the previous cycle. If another  $I^2C$  reading operation occurs, the bytes do not show the short). In general to observe a change in Diagnostic bytes, two  $I^2C$  reading operations are necessary.

#### I<sup>2</sup>C PROGRAMMING/READING SEQUENCE

A correct turn on/off sequence respectful of the diagnostic timings and producing no audible noises could be as follows (after battery connection):

TURN-ON: (STAND-BY OUT + DIAG ENABLE) --- 500 ms (min) --- MUTING OUT

TURN-OFF: MUTING IN --- 20 ms --- (DIAG DISABLE + STAND-BY IN)

Car Radio Installation: DIAG ENABLE (write) --- 200 ms --- I<sup>2</sup>C read (repeat until All faults disappear).

OFFSET TEST: Device in Play (no signal) -- OFFSET ENABLE - 30ms - I<sup>2</sup>C reading (repeat I<sup>2</sup>C reading until high-offset message disappears).

#### I<sup>2</sup>C BUS INTERFACE

Data transmission from microprocessor to the TDA7561 and viceversa takes place through the 2 wires I<sup>2</sup>C BUS interface, consisting of the two lines SDA and SCL (pull-up resistors to positive supply voltage must be connected).

#### **Data Validity**

As shown by fig. 19, the data on the SDA line must be stable during the high period of the clock.

The HIGH and LOW state of the data line can only change when the clock signal on the SCL line is LOW.

#### **Start and Stop Conditions**

As shown by fig. 20 a start condition is a HIGH to LOW transition of the SDA line while SCL is HIGH.

The stop condition is a LOW to HIGH transition of the SDA line while SCL is HIGH.

#### **Byte Format**

Every byte transferred to the SDA line must contain 8 bits. Each byte must be followed by an acknowledge bit. The MSB is transferred first.

#### **Acknowledge**

The transmitter\* puts a resistive HIGH level on the SDA line during the acknowledge clock pulse (see fig. 21). The receiver\*\* the acknowledges has to pull-down (LOW) the SDA line during the acknowledge clock pulse, so that the SDAline is stable LOW during this clock pulse.

#### \* Transmitter

- = master ( $\mu$ P) when it writes an address to the TDA7561
- = slave (TDA7561) when the  $\mu P$  reads a data byte from TDA7561

#### \*\* Receiver

- = slave (TDA7561) when the  $\mu P$  writes an address to the TDA7561
- = master (µP) when it reads a data byte from TDA7561

Figure 19. Data Validity on the I<sup>2</sup>CBUS

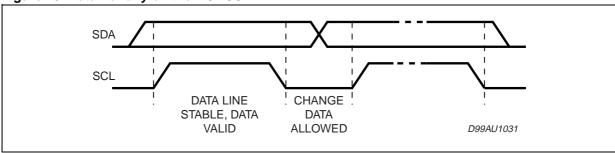


Figure 20. Timing Diagram on the I<sup>2</sup>CBUS

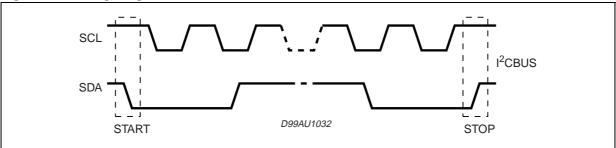
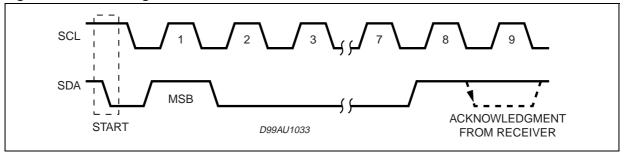


Figure 21. Acknowledge on the I<sup>2</sup>CBUS



#### **SOFTWARE SPECIFICATIONS**

All the functions of the TDA7561 are activated by  $I^2C$  interface.

The bit 0 of the "ADDRESS BYTE" defines if the next bytes are write instruction (from  $\mu P$  to TDA7561) or read instruction (from TDA7561 to  $\mu P$ ).

Chip Address:

D7							D0	
1	1	0	1	1	0	0	Х	D8 Hex

X = 0 Write to device

X = 1 Read from device

If R/W = 0, the mP sends 2 "Instruction Bytes": IB1 and IB2.

#### IB1

D7	X
D6	Diagnostic enable (D6 = 1) Diagnostic defeat (D6 = 0)
D5	Offset Detection enable (D5 = 1) Offset Detection defeat (D5 = 0)
D4	Front Channel Gain = 26dB (D4 = 0) Gain = 12dB (D4 = 1)
D3	Rear Channel Gain = 26dB (D3 = 0) Gain = 12dB (D3 = 1)
D2	Mute front channels (D2 = 0) Unmute front channels (D2 = 1)
D1	Mute rear channels (D1 = 0) Unmute rear channels (D1 = 1)
D0	x

### IB2

D7	Х
D6	used for testing
D5	used for testing
D4	Stand-by on - Amplifier not working - (D4 = 0) Stand-by off - Amplifier working - (D4 = 1)
D3	Power amplifier mode diagnostic (D3 = 0) Line driver mode diagnostic (D3 = 1)
D2	х
D1	X
D0	X

If R/W = 1, the TDA7561 sends 4 "Diagnostics Bytes" to  $\mu$ P: DB1, DB2, DB3 and DB4.

# DB1

D7	Thermal Warning active (D7 = 1)
D6	Diag. cycle not activated or not terminated (D6 = 0) Diag. cycle terminated (D6 = 1)
D5	X
D4	Channel LFTurn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
D3	Channel LF Normal load (D3 = 0) Short load (D3 = 1)
D2	Channel LFTurn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Offset diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)
D1	Channel LFNo short to Vcc (D1 = 0)Short to Vcc (D1 = 1)
D0	Channel LFNo short to GND (D1 = 0)Short to GND (D1 = 1)

# DB2

D7	Offset detection not activated (D7 = 0) Offset detection activated (D7 = 1)
D6	Х
D5	Х
D4	Channel LRTurn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
D3	Channel LRNormal load (D3 = 0) Short load (D3 = 1)
D2	Channel LRTurn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)
D1	Channel LR No short to Vcc (D1 = 0) Short to Vcc (D1 = 1)
D0	Channel LR No short to GND (D1 = 0) Short to GND (D1 = 1)

# DB3

D7	Stand-by status (= IB1 - D4)
D6	Diagnostic status (= IB1 - D6)
D5	X
D4	Channel RFTurn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
D3	Channel RFNormal load (D3 = 0) Short load (D3 = 1)
D2	Channel RF Turn-on diag.: No open load (D2 = 0) Open load detection (D2 = 1) Permanent diag.: No output offset (D2 = 0) Output offset detection (D2 = 1)
D1	Channel RFNo short to Vcc (D1 = 0) Short to Vcc (D1 = 1)
D0	Channel RFNo short to GND (D1 = 0) Short to GND (D1 = 1)

#### DB4

D7	X
D6	X
D5	X
D4	Channel RR Turn-on diagnostic (D4 = 0) Permanent diagnostic (D4 = 1)
D3	Channel RR Normal load (D3 = 0) Short load (D3 = 1)
D2	Channel RR Turn-on diag.: No open load (D2 = 0)
D1	Channel RRNo short to Vcc (D1 = 0)Short to Vcc (D1 = 1)
D0	Channel RRNo short to GND (D1 = 0)Short to GND (D1 = 1)

#### **Examples of bytes sequence**

1 - Turn-On diagnostic - Write operation

Start   Address byte with D0 = 0   ACK   IB1 with D6 = 1   ACK   IB2   ACK   STOR	Start	Address byte with D0 = 0	ACK	IB1 with D6 = 1	ACK	IB2	ACK	STOP
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2 - Turn-On diagnostic - Read operation

Start Address byte with D0 = 1 ACK DB1 ACK DB2 ACK DB3 ACK I	DB4 ACK	STOP
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The delay from 1 to 2 can be selected by software, starting from T.B.D. ms

3a - Turn-On of the power amplifier with 26dB gain, mute on, diagnostic defeat.

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
			X000000X		XXX1X0XX		

3b - Turn-Off of the power amplifier

Start	Address byte with D0 = 0	ACK	IB1	ACK	IB2	ACK	STOP
			X0XXXXXX		XXX0XXXX		

4 - Offset detection procedure enable

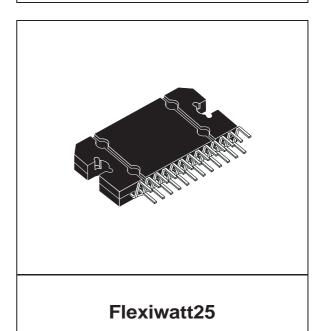
Start	Address byte with D0 = 0	ACK	IB1 ACI		IB2	ACK	STOP
			XX1XX11X		XXX1X0XX		

**5** - Offset detection procedure stop and reading operation (the results are valid only for the offset detection bits (D2 of the bytes DB1, DB2, DB3, DB4).

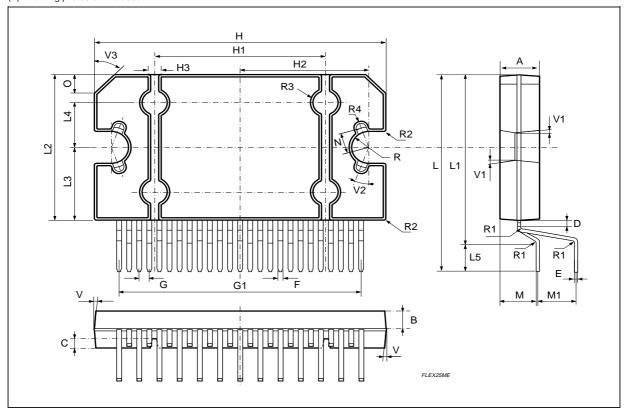
- The purpose of this test is to check if a D.C. offset (2V typ.) is present on the outputs, produced by input capacitor with anomalous leackage current or humidity between pins.
- The delay from 4 to 5 can be selected by software, starting from T.B.D. ms

D.114		mm			inch			
DIM.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
Α	4.45	4.50	4.65	0.175	0.177	0.183		
В	1.80	1.90	2.00	0.070	0.074	0.079		
С		1.40			0.055			
D	0.75	0.90	1.05	0.029	0.035	0.041		
E	0.37	0.39	0.42	0.014	0.015	0.016		
F (1)			0.57			0.022		
G	0.80	1.00	1.20	0.031	0.040	0.047		
G1	23.75	24.00	24.25	0.935	0.945	0.955		
H (2)	28.90	29.23	29.30	1.138	1.150	1.153		
H1		17.00			0.669			
H2		12.80			0.503			
H3		0.80			0.031			
L (2)	22.07	22.47	22.87	0.869	0.884	0.904		
L1	18.57	18.97	19.37	0.731	0.747	0.762		
L2 (2)	15.50	15.70	15.90	0.610	0.618	0.626		
L3	7.70	7.85	7.95	0.303	0.309	0.313		
L4		5			0.197			
L5		3.5			0.138			
M	3.70	4.00	4.30	0.145	0.157	0.169		
M1	3.60	4.00	4.40	0.142	0.157	0.173		
N		2.20			0.086			
0		2			0.079			
R		1.70			0.067			
R1		0.5			0.02			
R2		0.3			0.12			
R3		1.25			0.049			
R4	0.50 0.019							
V		5° (Typ.)						
V1	3° (Typ.)							
V2	20° (Typ.)							
V3	45° (Typ.)							

# OUTLINE AND MECHANICAL DATA



(1): dam-bar protusion not included (2): molding protusion included



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